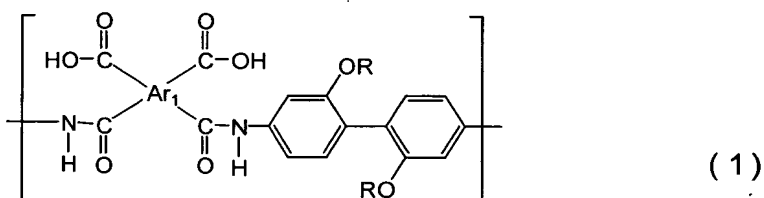


ABSTRACT

The present invention relates to an aromatic polyimide which has excellent heat resistance and excellent thermal dimensional stability, and which realizes low hygroscopic property, and an aromatic polyamic acid as a precursor for the aromatic polyimide. Provided are an aromatic polyamic acid including a structural unit represented by the following general formula (1), and an aromatic polyimide obtained by imidating the aromatic polyamic acid. The aromatic polyamic acid or the aromatic polyimide can be a copolymerization-type aromatic polyamic acid or aromatic polyimide having another structural unit:



where, Ar₁ represents a tetravalent organic group produced from a tetracarboxylic acid having one or more aromatic rings, and R represents a hydrocarbon having 2 to 6 carbon atoms.